



LTEM NO.: SIM-021 (Industrial)

(33.0L x 25.0W x 3.0H & MEMORY-CARD-SOCKETS)

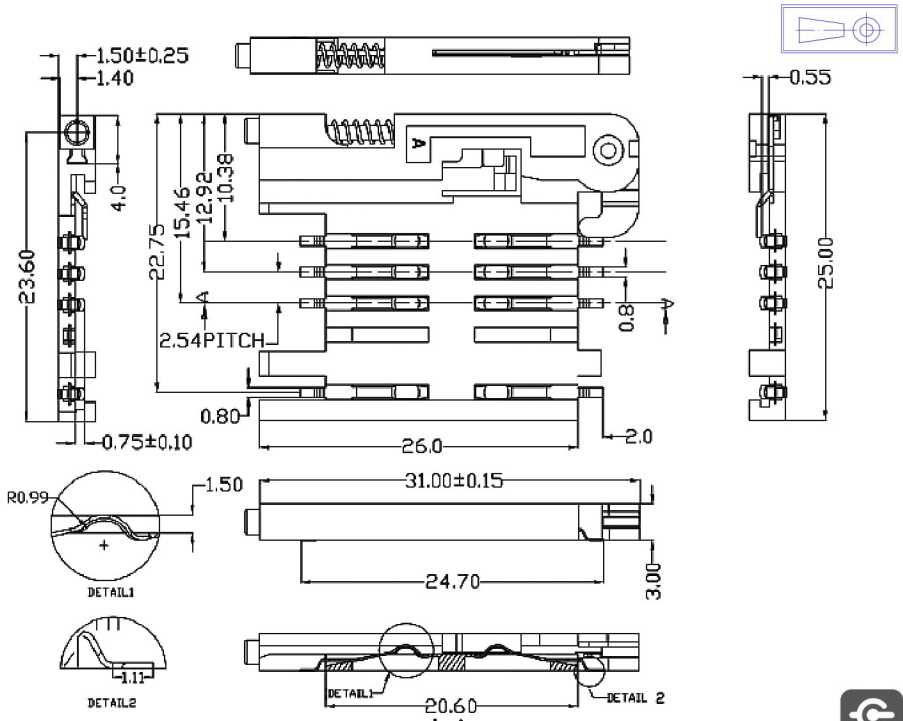
MINI SIM SOCKETS

Technical parameter

PROJECT	LEVEL	A[better product]
Electrical Properties	Contact Rating	25mA, 12V DC
	Initial Contact Resistance	50mΩ max.
Durable Performance	Insulation Resistance	100MΩ min. 500V DC
	Withstand Voltage	500V AC for 1 minute
	There No Load	10,000 Cycles
	Rated Load	8,500 Cycles
	Storage temp.	-40℃ ~ +85℃ (Operating Temp.)

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Unit:mm



CIRCUIT BOARD SIZE

(Vertical view)

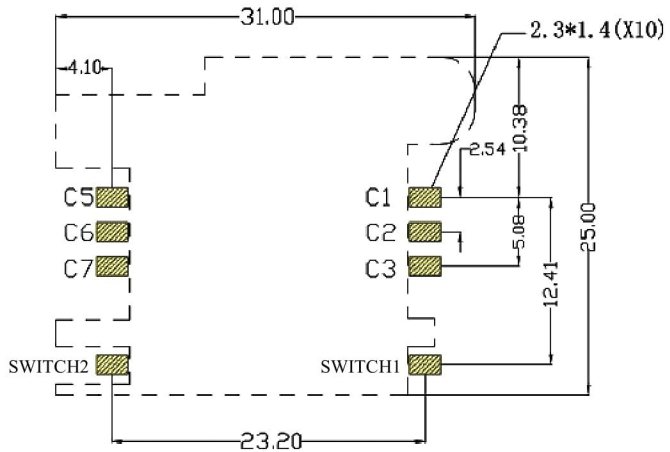
Operating Force

Inward
Exiting

8.0~12.0N. (1N.=100Gram Force)
12.5N. [± 200 gf]

Solder-ability (Max.)

IR Reflow: 250°C, 3sec. Manual: 350°C, 3sec.

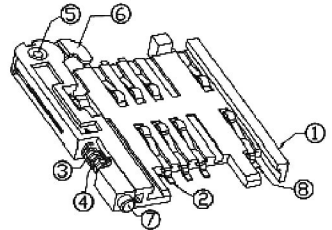


Pin definition



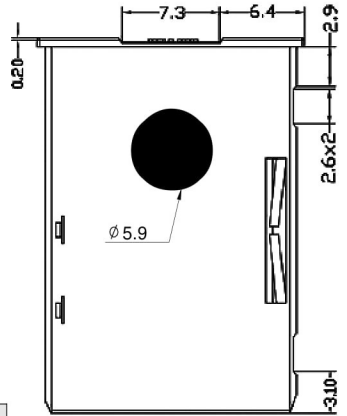
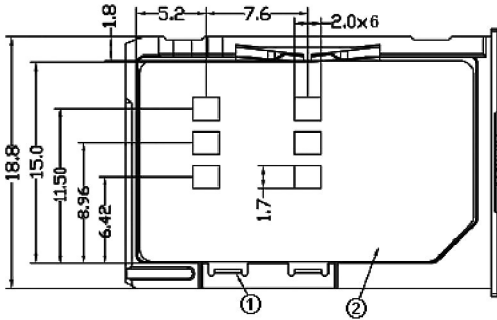
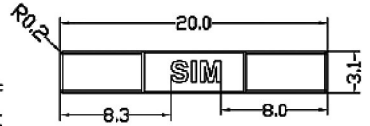
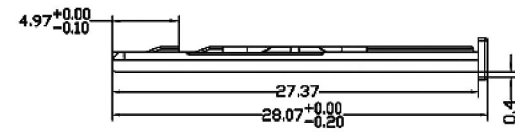
Material declaration

No.	NAME	MATERIAL	PLATING
①	BASE	LCP (Black)	-
②	DATA CONTACT	C5210 (50 μ * 15 μ)	6-gold-plating
③	SPRING	SUS301	-
④	PUSH ROD	Q345	-
⑤	ROLLER	Brass (\square 1.1mm)	-
⑥	TOGGLE LEVER	SUS301 $\rho=0.40$	-
⑦	HANDLE	PPS/LCP	-
⑧	SWITCH PIN	C5210 (50 μ * 15 μ)	gold-plating



Pin No.	Type	Description
C ①	1	VCC
C ②	1	RST
C ③	1	CLK
C ⑤	1	GND
C ⑥	1	VPP
C ⑦	1	I/O
SWITCH1	1	Cd switch1
SWITCH2	1	Cd switch2

Products do not belong to hazardous waste, When waste can recycling processing



No.	NAME	MATERIAL
①	TERMINAL	PHOSPHOR BROMZE(T=0.15mm)
②	COVER	PBT+30%G.F (Black)

SPECIFIED TOLERANCES UNLESS OTHERWISE

DECIMALS	ANGLES
X : ±0.50	X : ±3°
X.X : ±0.35	X.X : ±1°
X.XX : ±0.15	

Please practice according to below condition:

- (1) Preheat : 150 °C 90-120s
- (2) Soldering heat : 250 °C Max 3S.
- (3) Immersion depth: Up to the surface of the board

